

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

ST2045-MS

Product specification

FEATURES

- Excellent high temperature stability
- Low forward voltage
- Low power loss/ high efficiency
- High forward surge capability
- Ideal for automated placement
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition


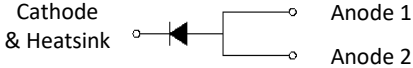

MECHANICAL DATA

- **Case:** TO-277
Molding compound meets UL 94 V-0 flammability rating
Moisture sensitivity level: level 1, per J-STD-020
- **Terminal:** Matte tin plated leads, solderable per JESD22-B102
Meet JESD 201 class 2 whisker test
- **Polarity:** Indicated by cathode band
- **Weight:** 0.095g (approximately)

TYPICAL APPLICATIONS

Schottky barrier rectifier is designed for high frequency miniature switched mode power supplies such as adapters, lighting and on-board DC/DC converters.

Reference News

TO-277	PIN CONFIGURATION	MARKING
		

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER			SYMBOL	SB2045L	UNIT
Maximum repetitive peak reverse voltage			V_{RRM}	45	V
Maximum average forward rectified current			$I_{F(AV)}$	20	A
Peak forward surge current, 8.3 ms singlehalf sine-wave superimposed on rated load per diode			I_{FSM}	250	A
Maximum instantaneous forward voltage per diode (Note 1)	$I_F = 20\text{A}$	$T_J = 25^{\circ}\text{C}$	V_F	0.55	V
Maximum instantaneous reverse current per diode at rated reverse voltage		$T_J = 25^{\circ}\text{C}$	I_R	100	μA
Typical thermal resistance			$R_{\theta JL}$	11	$^{\circ}\text{C/W}$
Operating temperature range			T_J	- 55 to +150	$^{\circ}\text{C}$
Storage temperature range			T_{STG}	- 55 to +150	$^{\circ}\text{C}$

 Note 1: Pulse Test with Pulse Width=300 μs , 1% Duty Cycle

RATINGS AND CHARACTERISTICS CURVES ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

FIG.1 FORWARD CURRENT DERATING CURVE

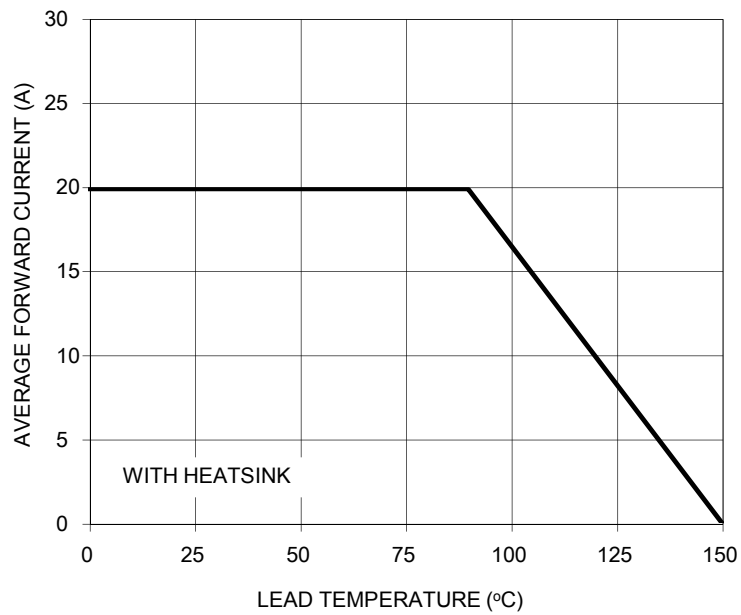


FIG. 2 TYPICAL FORWARD CHARACTERISTICS

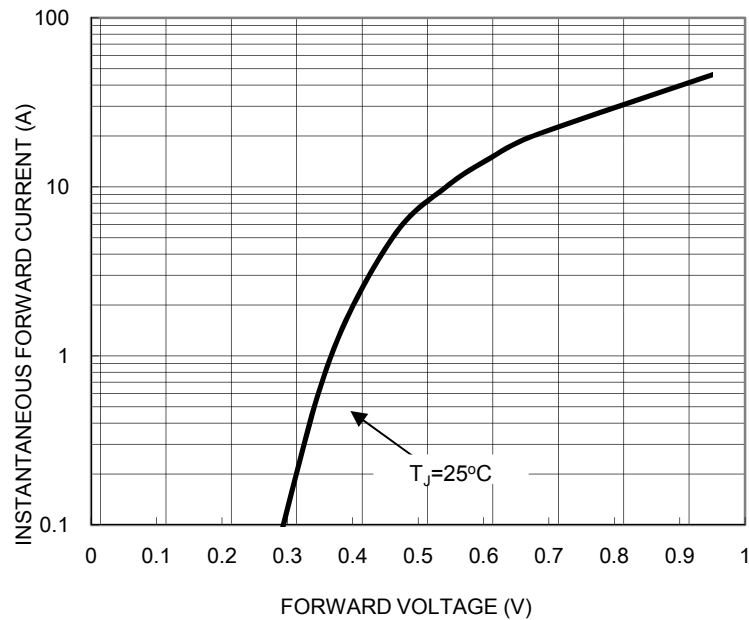


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

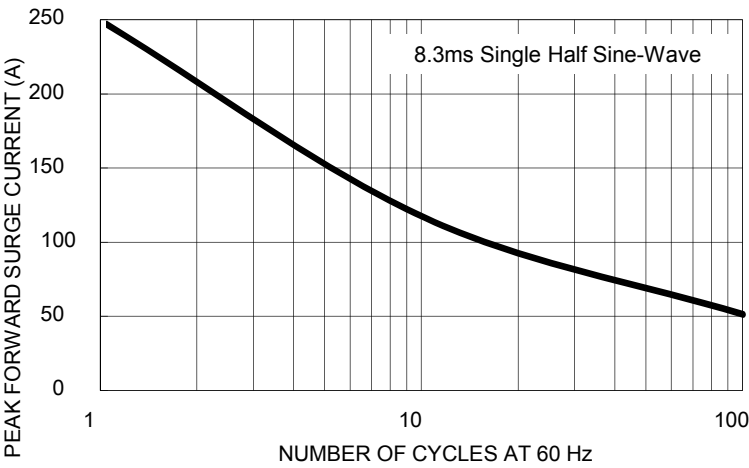


FIG. 4 TYPICAL REVERSE CHARACTERISTICS

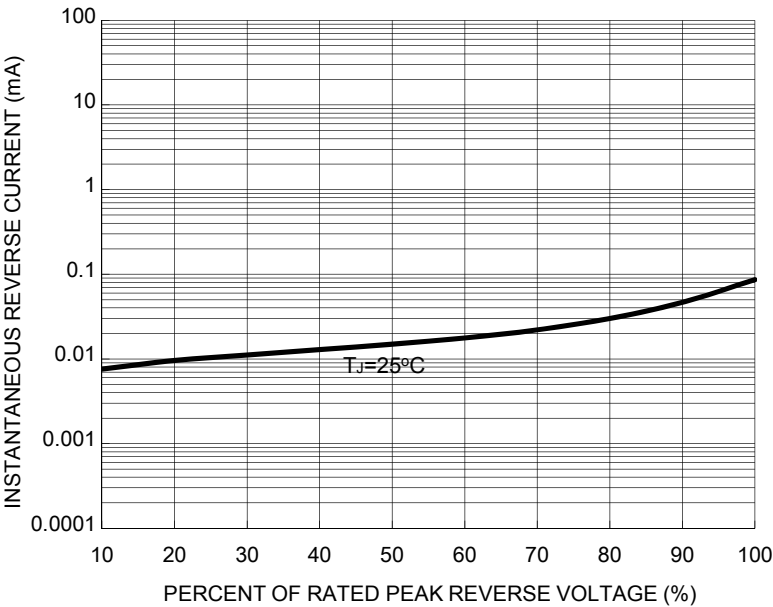
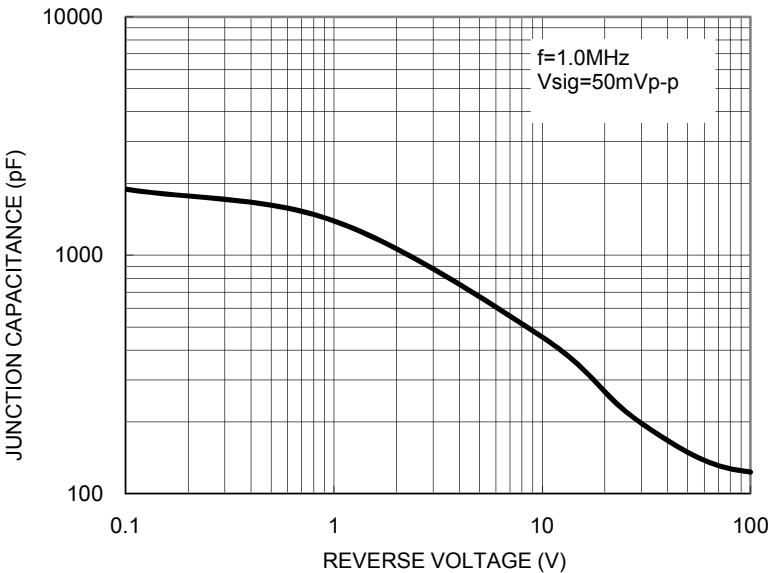
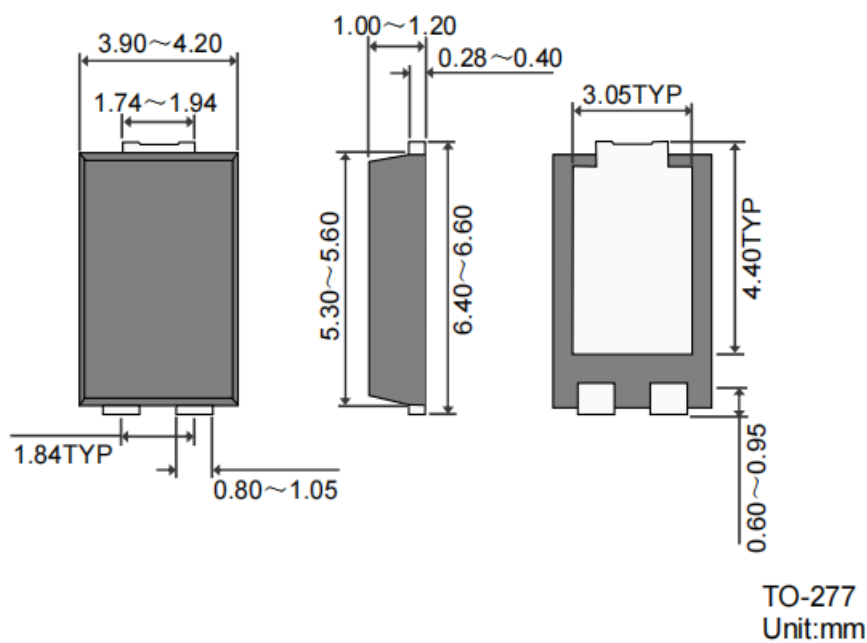


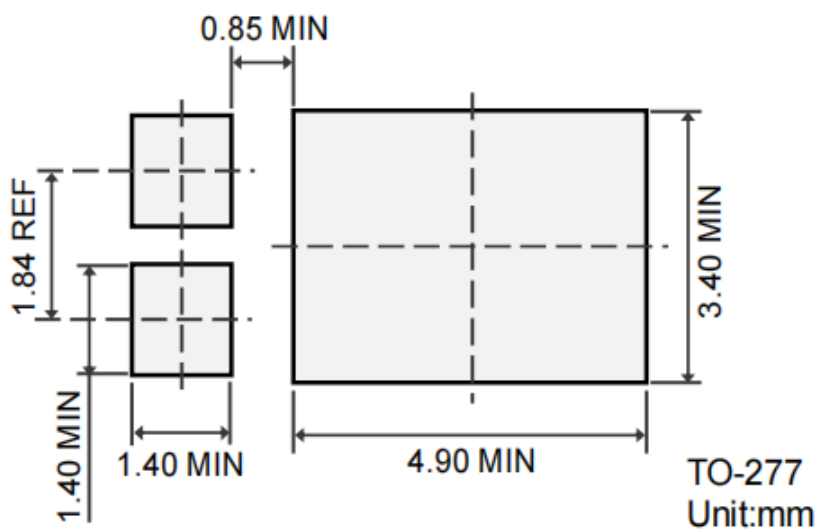
FIG. 5 TYPICAL JUNCTION CAPACITANCE



Package Outline Dimensions



Suggested Solder Pad Layout



REEL SPECIFICATION

P/N	PKG	QTY
ST2045-MS	TO-277	5000

Attention

■ Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.

■ MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specification of any and all MSKSEMI Semiconductor products described or contained herein.

■ Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

■ MSKSEMI Semiconductor strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

■ In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

■ No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.

■ Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringement of intellectual property rights or other rights of third parties.

■ Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the MSKSEMI Semiconductor product that you intend to use.